



# DCR2760M85

# **Phase Control Thyristor**

DS6078-1 September 2012 (LN29818)

## **FEATURES**

- Double Side Cooling
- High Surge Capability

## **APPLICATIONS**

- High Power Drives
- High Voltage Power Supplies
- Static Switches

## **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Voltages V <sub>DRM</sub> and V <sub>RRM</sub> V	Conditions
DCR2760M85* DCR2760M80 DCR2760M75 DCR2760M70	8500 8000 7500 7000	$\begin{split} T_{vj} &= \text{-}40 ^{\circ}\text{C to 125} ^{\circ}\text{C}, \\ I_{DRM} &= I_{RRM} = 300 \text{mA}, \\ V_{DRM}, V_{RRM}  t_p &= 10 \text{ms}, \\ V_{DSM}  \&  V_{RSM} &= \\ V_{DRM}  \&  V_{RRM} + 100 V \\ respectively \end{split}$

Lower voltage grades available. \*8200V @ -40°C, 8500V @ 0°C

## **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

## DCR2760M85

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

#### **KEY PARAMETERS**

$V_{DRM}$	8500V
I <sub>T(AV)</sub>	2765A
I <sub>TSM</sub>	32500A
dV/dt*	1500V/µs
dl/dt	200A/μs

## \* Higher dV/dt selections available

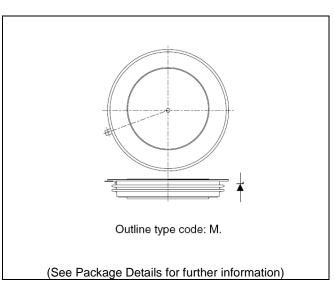


Fig. 1 Package outline



## **CURRENT RATINGS**

## T<sub>case</sub> = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions		Units
Double Sid	de Cooled			
I <sub>T(AV)</sub>	Mean on-state current	Half wave resistive load	2765	А
I <sub>T(RMS)</sub>	RMS value	-	4343	А
I <sub>T</sub>	Continuous (direct) on-state current	-	4083	А

## **SURGE RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
I <sub>TSM</sub>	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 125$ °C	32.5	kA
l <sup>2</sup> t	I <sup>2</sup> t for fusing	$V_R = 0$	5.28	MA <sup>2</sup> s

## THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance – junction to case	Double side cooled	DC	-	0.00518	°C/W
		Single side cooled	Anode DC	1	0.01012	°C/W
			Cathode DC	1	0.01080	°C/W
R <sub>th(c-h)</sub>	Thermal resistance – case to heatsink	Clamping force 83.0kN	Double side	ı	0.001	°C/W
		(with mounting compound)	Single side	1	0.002	°C/W
$T_{vj}$	Virtual junction temperature	Blocking V <sub>DRM</sub> / V <sub>RRM</sub>		ı	125	°C
T <sub>stg</sub>	Storage temperature range			-55	125	°C
F <sub>m</sub>	Clamping force			74.0	91.0	kN





## **DYNAMIC CHARACTERISTICS**

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I <sub>RRM</sub> /I <sub>DRM</sub>	Peak reverse and off-state current	At V <sub>RRM</sub> /V <sub>DRM</sub> , T <sub>case</sub> = 125°C		-	300	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% $V_{DRM}$ , $T_j = 125$ °C, ga	ate open	-	1500	V/µs
dI/dt	Rate of rise of on-state current	From 67% V <sub>DRM</sub> to 2x I <sub>T(AV)</sub>	Repetitive 50Hz	-	100	A/µs
		Gate source 30V, 10Ω,	Non-repetitive	-	200	A/µs
		$t_r < 0.5 \mu s, T_j = 125$ °C				
$V_{T(TO)}$	Threshold voltage – Low level	500 to 1600A at T <sub>case</sub> = 125°	С	-	0.9	V
	Threshold voltage – High level	1600 to 4000A at T <sub>case</sub> = 125	i°C	-	1.18	V
r <sub>T</sub>	On-state slope resistance – Low level	500A to 1600A at T <sub>case</sub> = 125°C		-	0.65	mΩ
	On-state slope resistance – High level	1600A to 4000A at T <sub>case</sub> = 125°C		-	0.46	mΩ
t <sub>gd</sub>	Delay time	$V_D = 67\% V_{DRM}$ , gate source 30V, $10\Omega$		-	3	μs
	,	$t_r = 0.5 \mu s, T_j = 25^{\circ}C$				
t <sub>q</sub>	Turn-off time	$I_T = 3000A, T_j = 125^{\circ}C,$ $V_R = 200V, dI/dt = 1A/\mu s,$			1000	μs
		dV <sub>DR</sub> /dt = 20V/μs linear				
Qs	Stored charge	$I_T = 3000 A, T_j = 125 ^{\circ} C, dI/dt - 1A/\mu s, V_{Rpeak} \sim 5100 V, V_R \sim 3400 V$		5150	7950	μC
ΙL	Latching current	$T_j = 25$ °C, $V_D = 5V$		-	3	A
l <sub>H</sub>	Holding current	$T_j = 25^{\circ}C, R_{G-K} = \infty, I_{TM} = 500A, I_T = 5A$			300	mA



## **GATE TRIGGER CHARACTERISTICS AND RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
$V_{GT}$	Gate trigger voltage	$V_{DRM} = 5V$ , $T_{case} = 25$ °C	1.5	V
$V_{GD}$	Gate non-trigger voltage	At 50% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	0.4	V
I <sub>GT</sub>	Gate trigger current	$V_{DRM} = 5V$ , $T_{case} = 25$ °C	400	mA
I <sub>GD</sub>	Gate non-trigger current	At 50% V <sub>DRM</sub> , T <sub>case</sub> = 125°C	10	mA

## **CURVES**

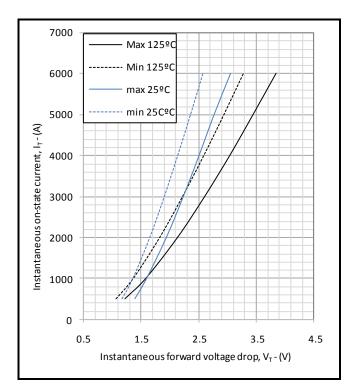


Fig.2 Maximum & minimum on-state characteristics

 $V_{\mathsf{TM}}$  EQUATION

 $V_{TM} = A + BIn (I_T) + C.I_T + D.\sqrt{I_T}$ 

Where A = -0.224010

B = 0.1725829

C = 0.000292

D = 0.01039

these values are valid for  $T_j = 125^{\circ}C$  for  $I_T$  500A to 4200A

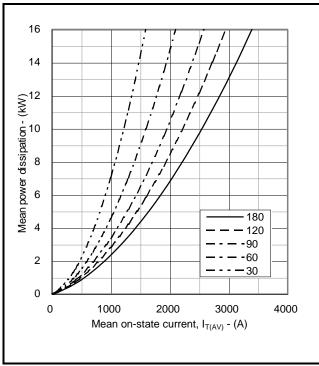


Fig.3 On-state power dissipation - sine wave

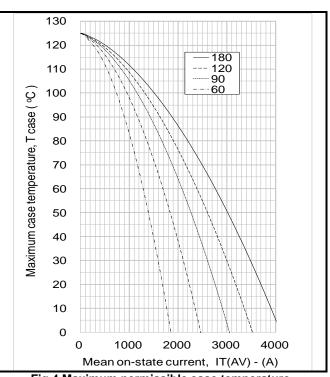


Fig.4 Maximum permissible case temperature, double side cooled – sine wave

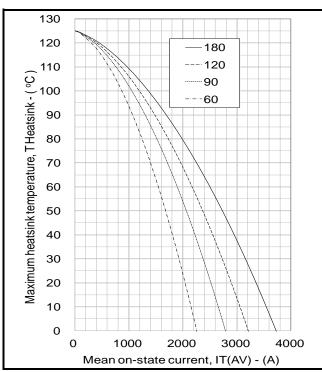


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

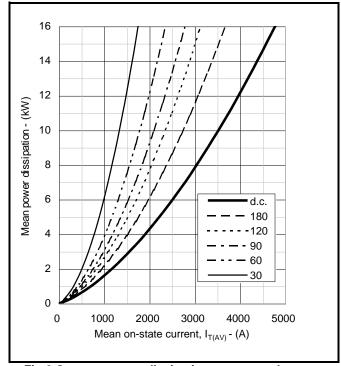


Fig.6 On-state power dissipation - rectangular wave



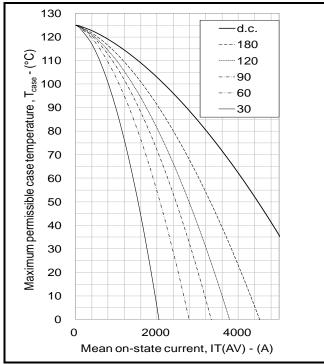


Fig.7 Maximum permissible case temperature, double side cooled – rectangular wave

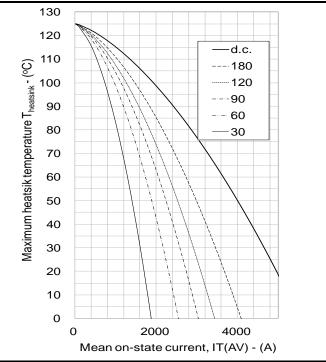
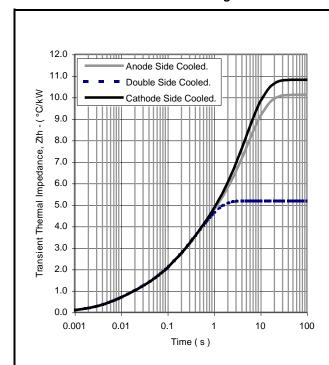


Fig.8 Maximum permissible heatsink temperature, double side cooled – rectangular wave



		1	2	3	4
Double side cooled	R <sub>i</sub> (°C/kW)	1.995338	1.242784	1.9448	0.005
Double side cooled	T <sub>i</sub> (s)	0.05	0.592935	0.592385	110.5108
Anode side cooled	R <sub>i</sub> (°C/kW)	6.092995	1.957372	2.042252	0.035908
Ariode side cooled	T <sub>i</sub> (s)	5.459764	0.510898	0.05	110.1735
Cathode side cooled	R <sub>i</sub> (°C/kW)	6.856845	1.876401	2.062845	0.025343
Callibue side cooled	T; (s)	5.181139	0.557321	0.05	110.1546

$$Z_{th} = \sum_{i=1}^{i=4} [R_i \times (1 - \exp(T/T_i))]$$

## $\Delta R_{th(j-c)}$ Conduction

Tables show the increments of thermal resistance  $R_{\text{th(j-c)}}$  when the device operates at conduction angles other than d.c.

0.36

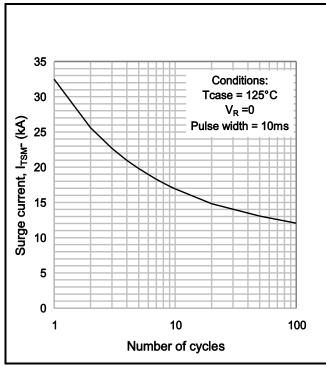
0.57

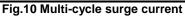
0.64

D	ouble side c		Ar	node Side			
	$\Delta Z_{th}$ (z)				$\Delta Z_{ti}$		
θ°	sine.	rect.		θ°	sine.		
180	0.51	0.36		180	0.51		
120	0.57	0.49		120	0.58		
90	0.64	0.56		90	0.65		
60	0.70	0.63		60	0.71		
30	0.74	0.71		30	0.75		
4	0.70	0.74		4.5	0.77		

Call	Cathode Sided Cooling				
	$\Delta Z_{th}(z)$				
θ°	sine.	rect.			
180	0.51	0.36			
120	0.58	0.50			
90	0.65	0.57			
60	0.71	0.64			
30	0.75	0.71			
1	77	٥,			

Fig.9 Maximum (limit) transient thermal impedance - junction to case (°C/kW)





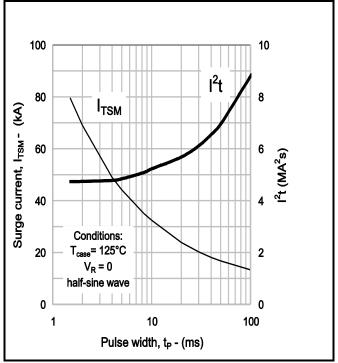


Fig.11 Single-cycle surge current

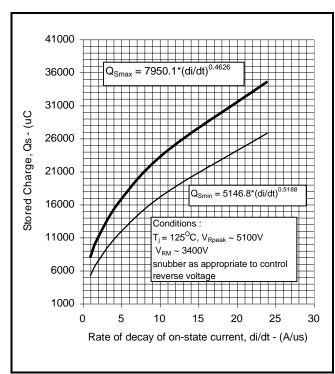


Fig.12 Stored charge

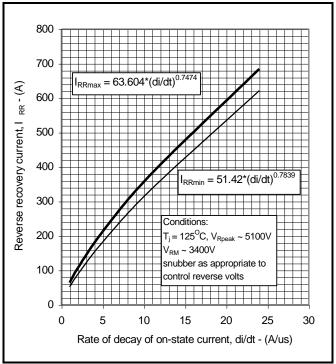


Fig.13 Reverse recovery current

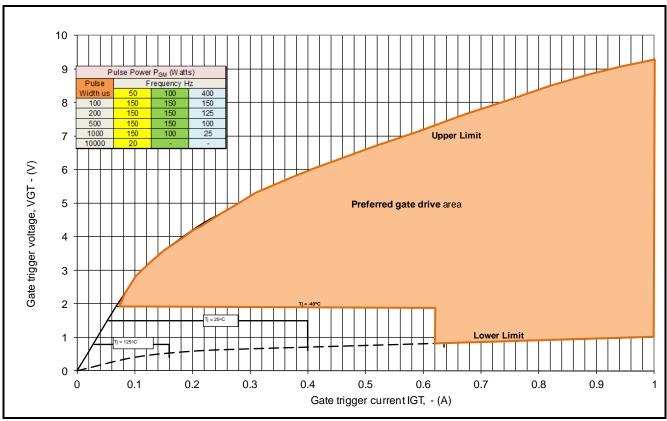


Fig14 Gate Characteristics

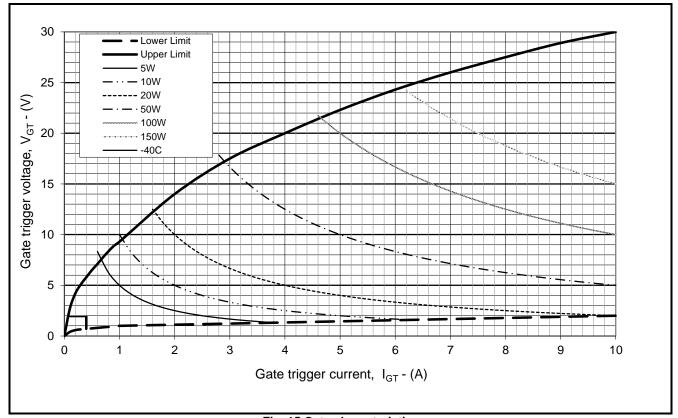


Fig. 15 Gate characteristics





## **PACKAGE DETAILS**

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

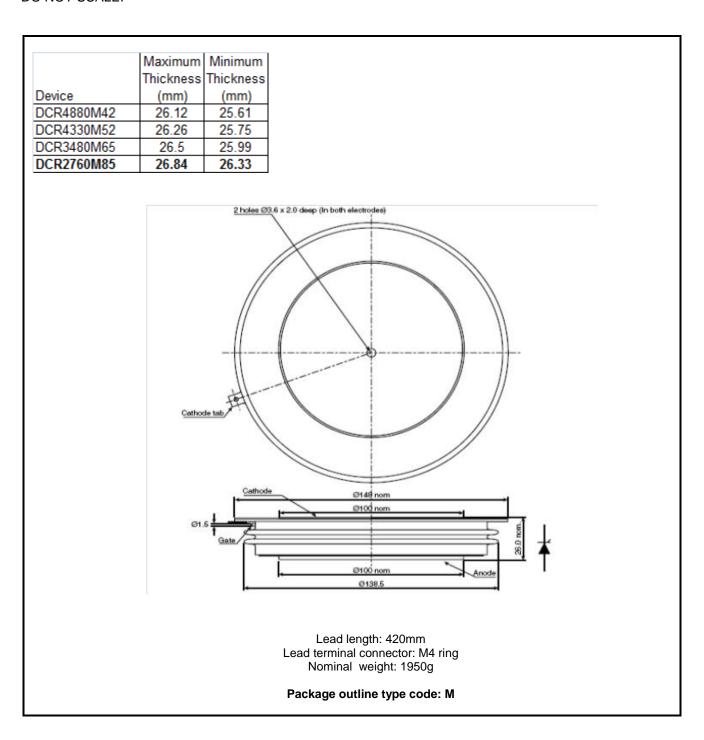


Fig.16 Package outline





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